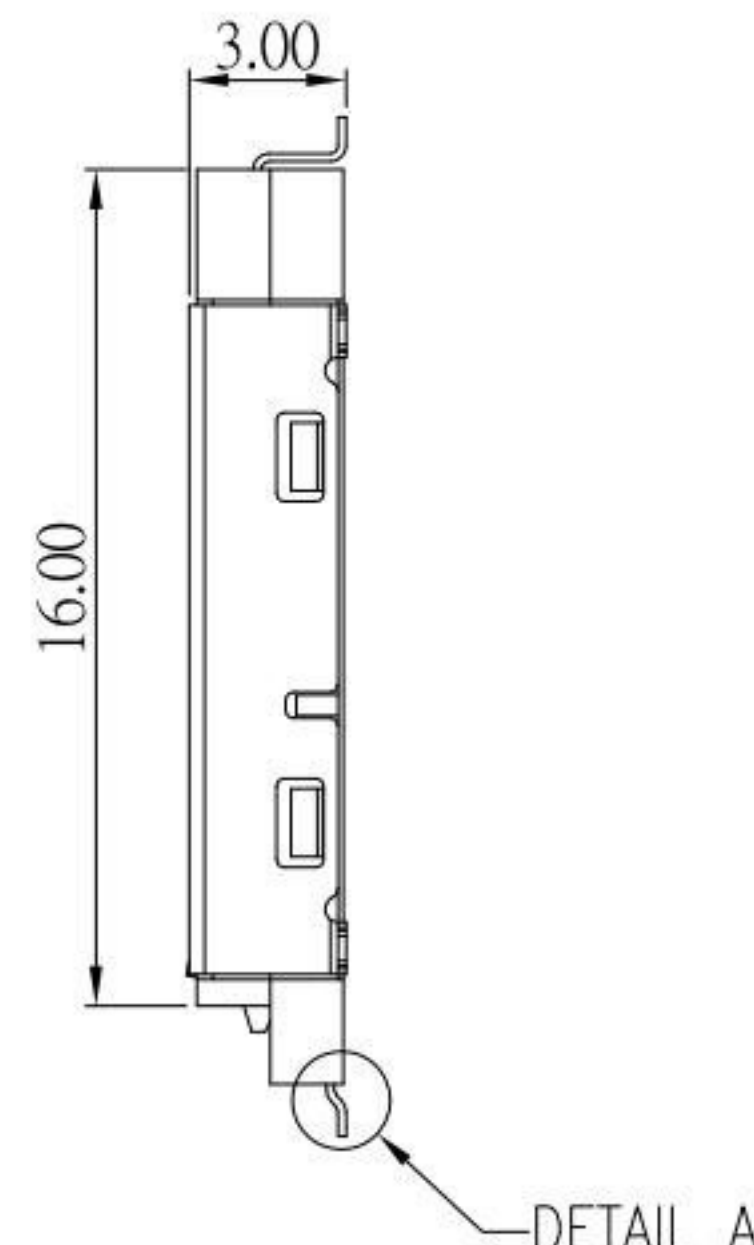
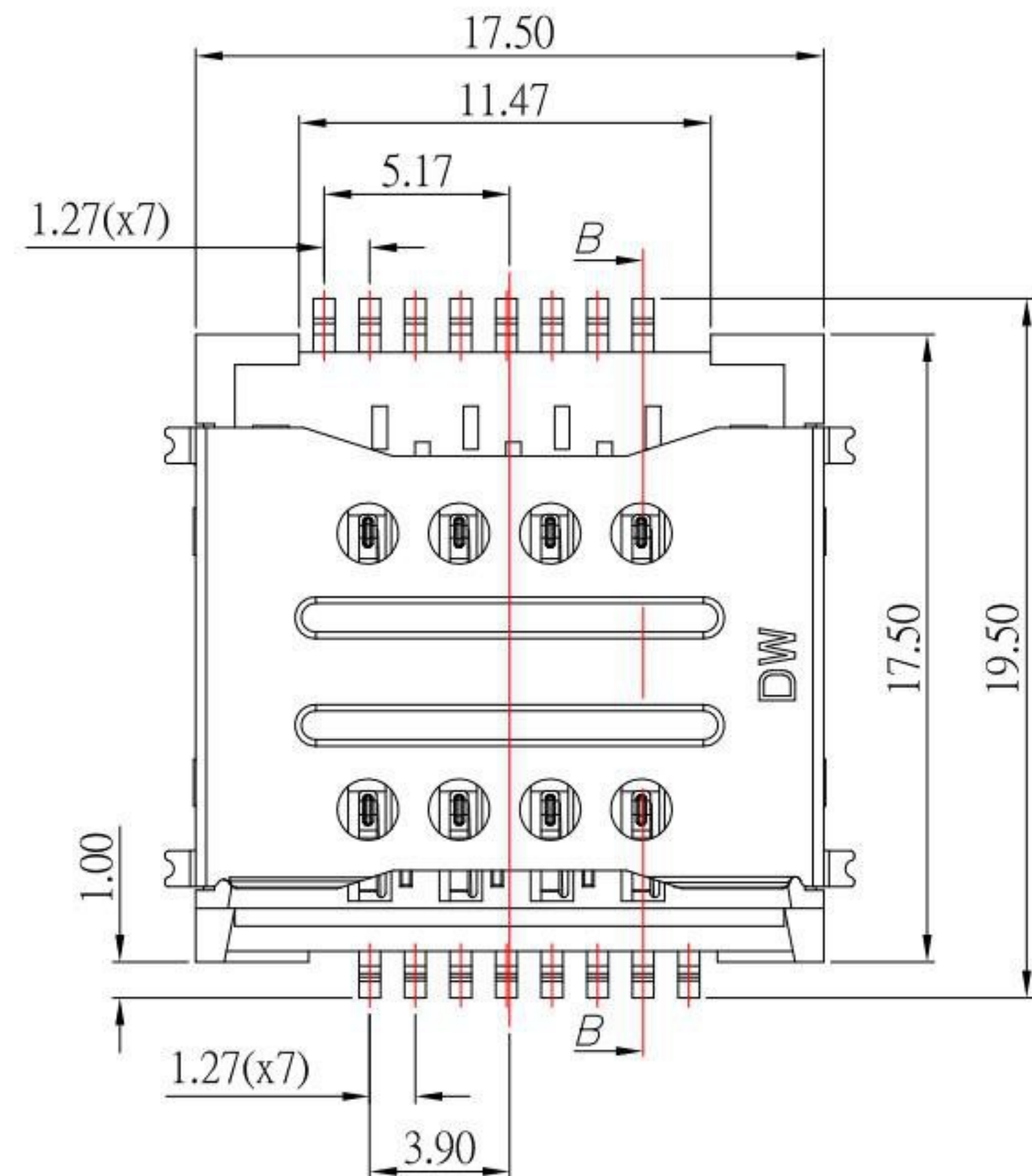
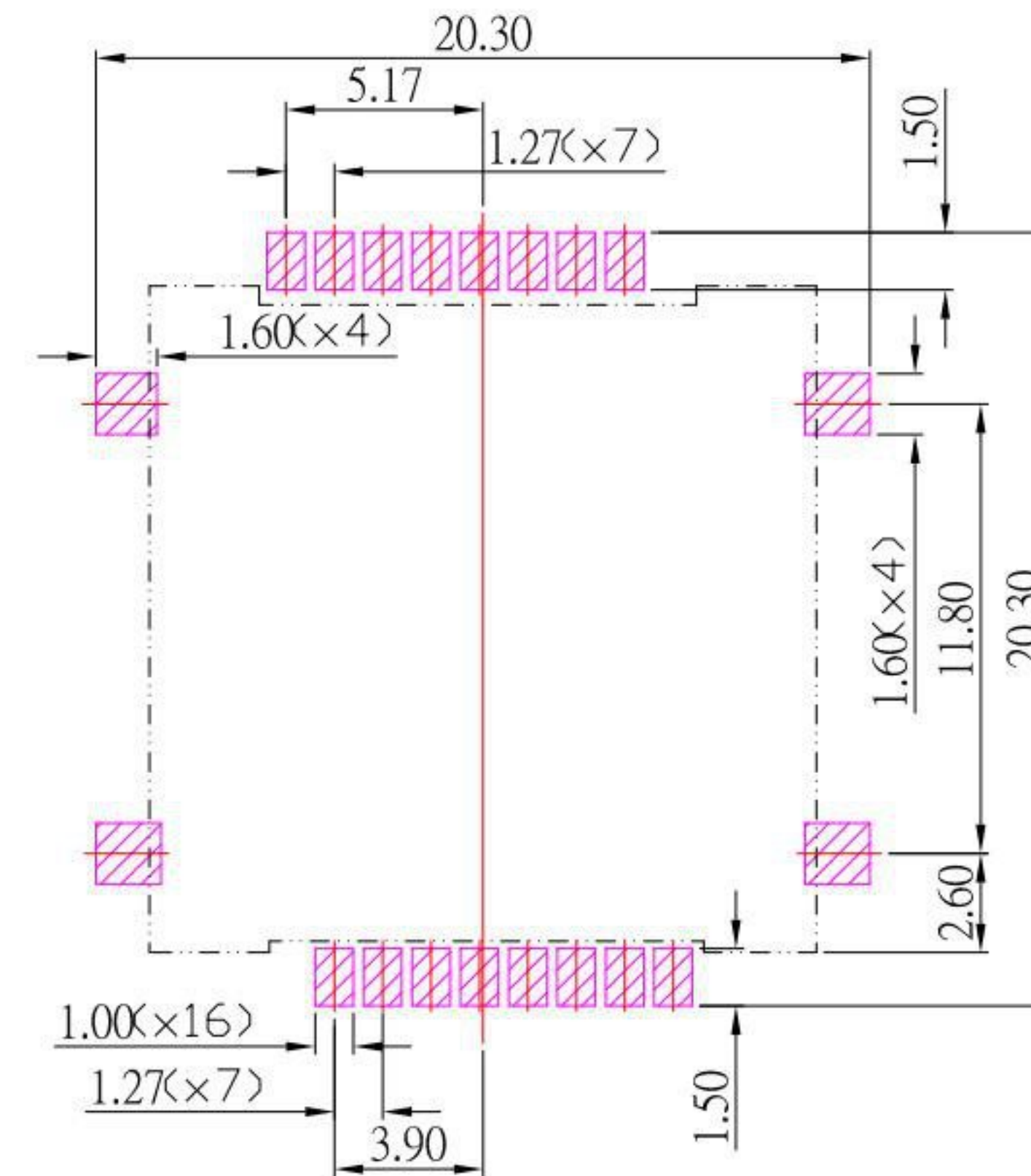
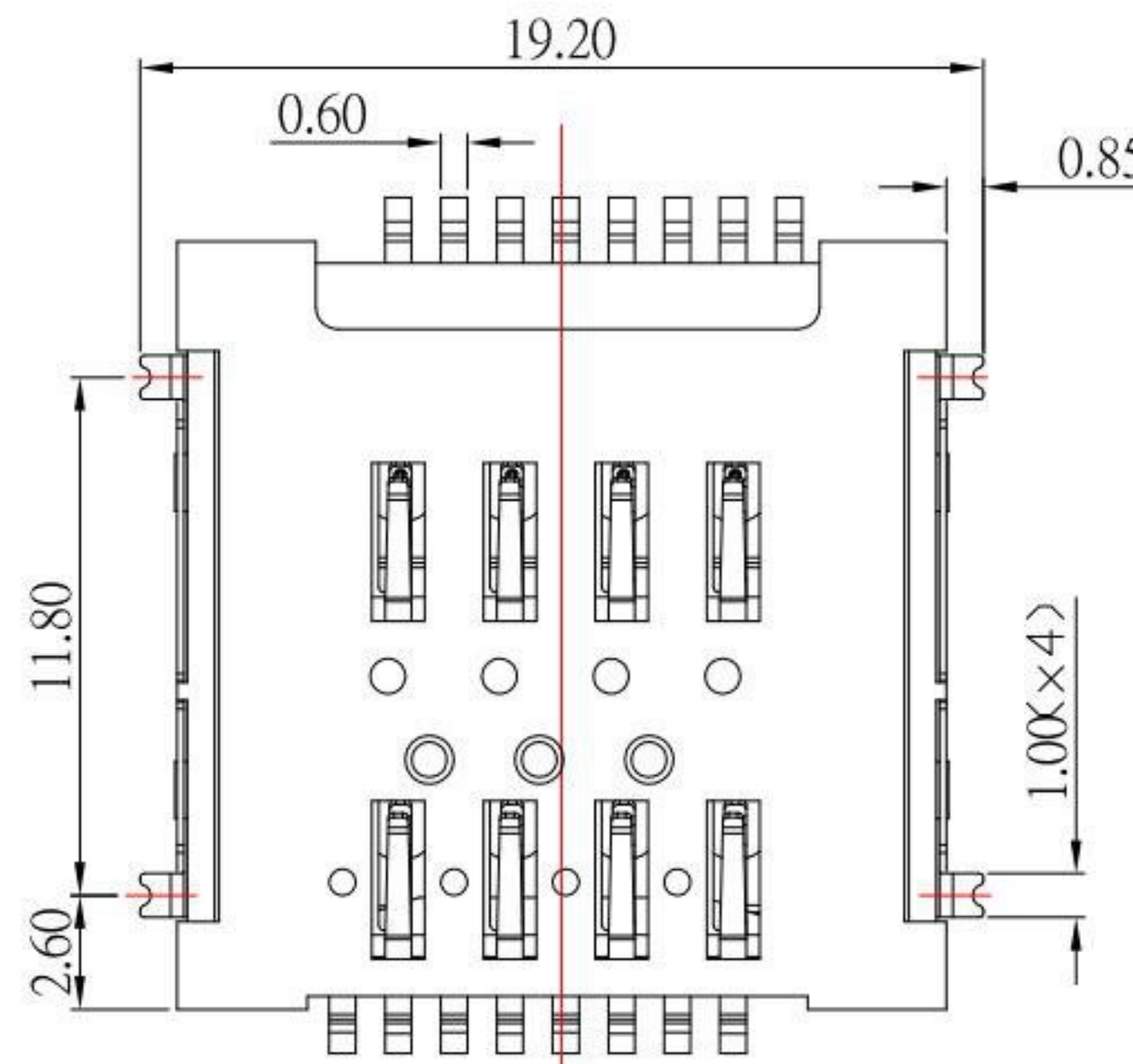


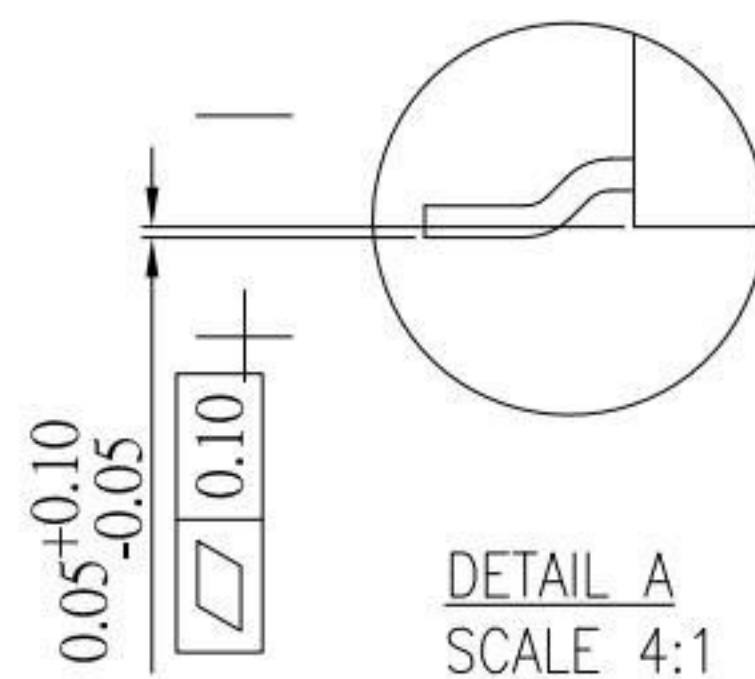
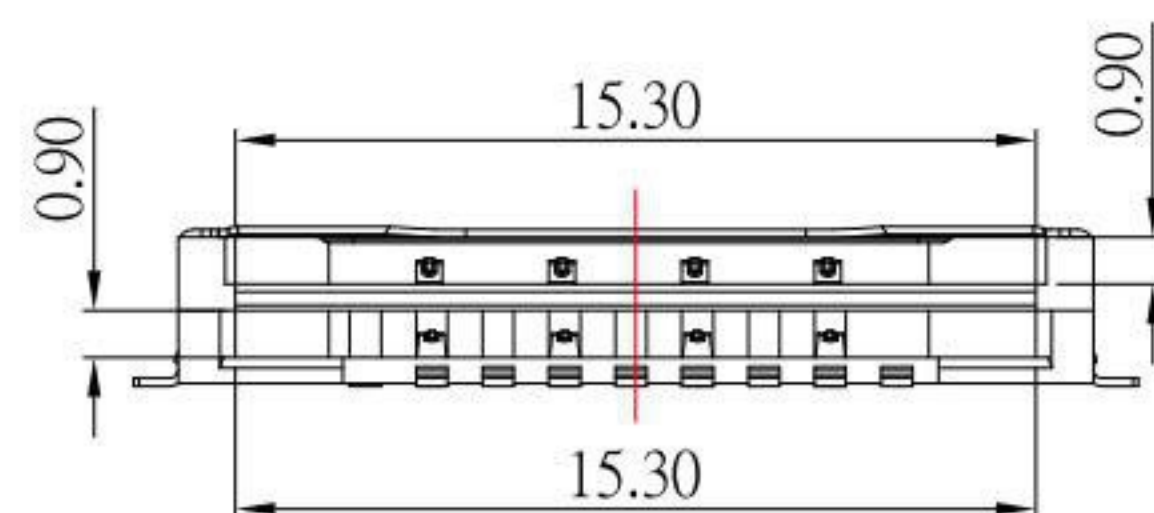
SECTION B-B



DETAIL A



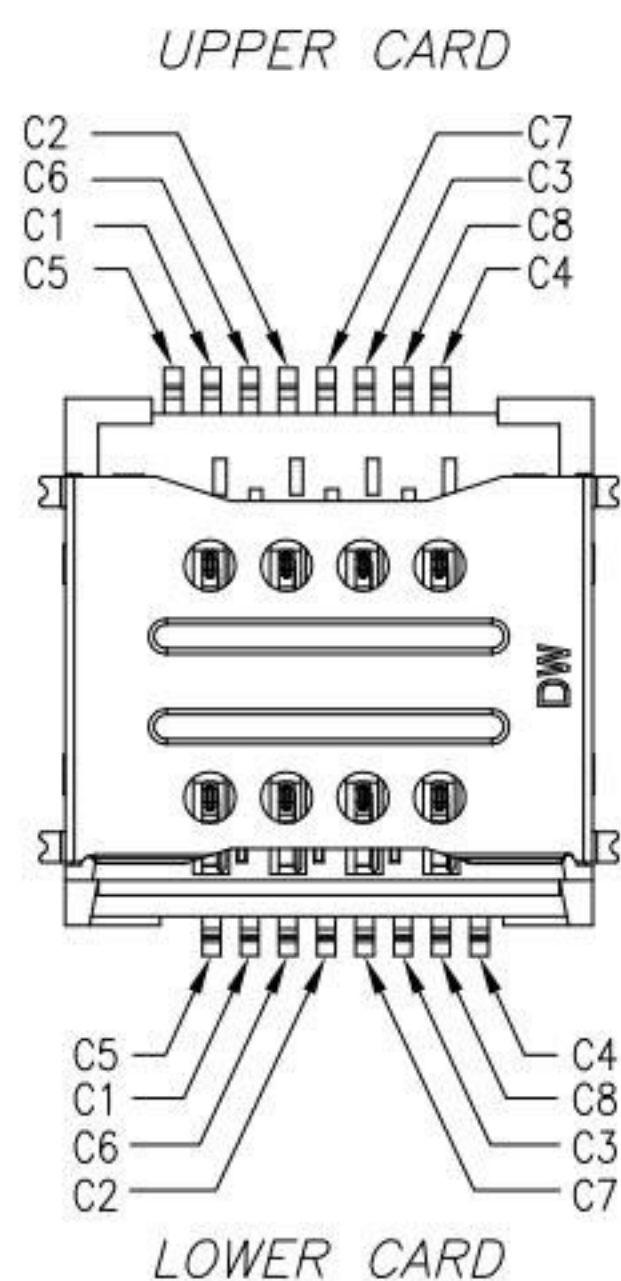
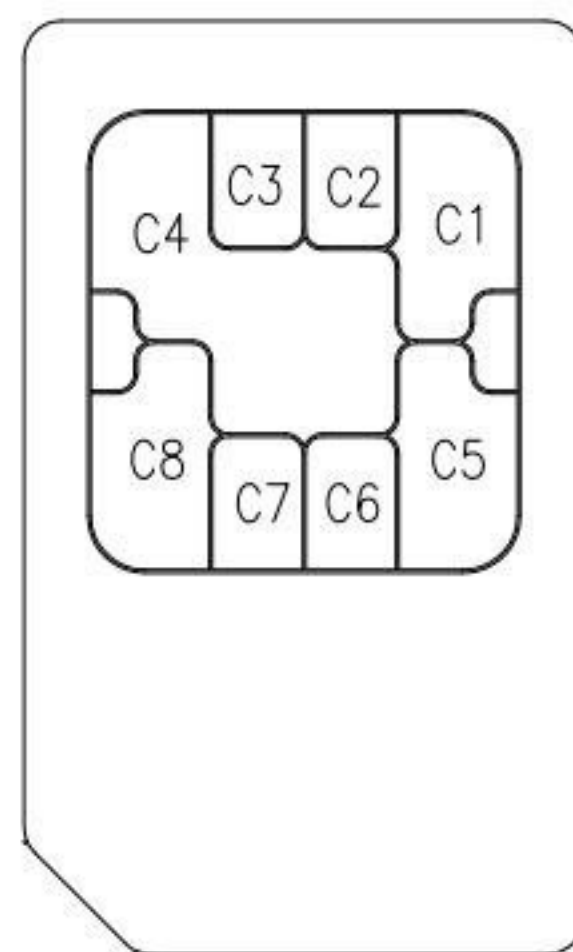
P.C.B LAYOUT MOUNTING PATTERN



DETAIL A  
SCALE 4:1

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED

SIM CARD CIRCUIT



MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : COPPER ALLOY
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;  
TIN PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

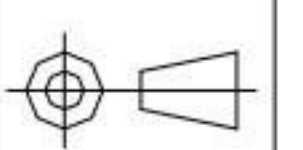
SPECIFICATION:

1. INSULATION RESISTANCE : 1000MΩ MIN.
2. CONTACT RESISTANCE : 50mΩ MAX.
3. Dielectric Withstanding Voltage: 350V AC
4. Durability: 3000 cycles

**KSD** 科斯达电子科技有限公司  
SWITCH CONNECTOR KSD ELECTRONIC TECHNOLOGY Co., LTD  
全球 互联零组件制造企业

TOLERANCE UNLESS OTHERWISE STATED :  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu  
DATE: 02/27/19  
CHECKED BY: Jacky Chen  
DATE: 02/27/19  
APPROVED BY: Tony Kao  
DATE: 02/27/19

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	雙層SIM卡座H3.0
SCALE	DWG NO.	SIM-216D202-S267
SHEET NO.	PART NO.	SIM-216D202-S267

SIZE: A4  
VER: R